Smart Windows Market - Analysis and Forecast (2014 - 2020): By Technology (Passive, Active On-Demand, Photochromic, Thermochromic, PDLC, SPD, EC); By Application (Automotive, Commercial, Residential, Aerospace) and Geography

Description: Smartglass and its main application of smart windows are the current focus of the global glass industry. Disruptive technologies are being seen right from the start of the value chain (materials) and are continuing till the smart windows manufacturers. Climate control, energy savings are the primary reasons behind the renewed interest in the global market.

This report gives an in-depth analysis and segmentation of the global smart windows market. The market is segmented by technology, applications, geographic regions and key countries. The market is also analyzed from the materials and thin film manufacturers to give a comprehensive understanding of the smart glass and smart windows market. Pricing analysis and value chain analysis will give key insights into the value addition as well as the market pricing scenario. Forecasts are provided for all the market segmentation for the period 2015 -2020.

Competitive landscape for each of the product types is highlighted and market players are profiled with attributes of company overview, financial overview, business strategies, product portfolio and recent developments. Market shares of the key players for 2012 are provided. The prominent players profiled in this report are ABB, Schneider Electric, Assa Abloy, Honeywell International and others.

The report contains the most detailed and in-depth segmentation of the Smart windows market.

Contents:
1. Global Semiconductor IP - Market Overview
2. Executive Summary
3. Global Semiconductor IP - Market Landscape
   3.1. Market Share Analysis
   3.2. Comparative Analysis
   3.2.1. Product Benchmarking
   3.2.2. End user profiling
   3.2.3. Patent Analysis
   3.2.4. Top 5 Financials Analysis
4. Global Semiconductor IP - Market Forces
   4.1. Market Drivers
   4.2. Market Constraints
   4.3. Market Challenges
   4.4. Attractiveness of the Semiconductor IP Industry
   4.4.1. Power of Suppliers
   4.4.2. Power of Customers
   4.4.3. Threat of New entrants
   4.4.4. Threat of Substitution
   4.4.5. Degree of Competition
5. Global Semiconductor IP - Strategic Analysis
   5.1. Pricing Analysis
   5.2. Opportunities Analysis
   5.3. Product/Market Life Cycle Analysis
   5.4. Semiconductor IP Market - SoC Vs SiP
   5.5. Semiconductor IP - Impact of Free and Open Source IP Cores
6. Global Semiconductor IP Market - Analysis by Types
   6.1. IP Cores
   6.1.1. Hard IP Cores
   6.1.2. Soft IP Cores
   6.2. Customization
6.2.1. Standard IP Core
6.2.2. Customizable IP Core
6.3. Form Factor
6.3.1. ASIC IP
6.3.1.1. For Integrated Circuits
6.3.1.2. For System-on-Chip
6.3.2. Programmable IP
6.3.2.1. For Integrated Circuits
6.3.2.2. For System-on-Chip
6.3.3. Digital IP
6.3.3.1. For Integrated Circuits
6.3.3.2. For System-on-Chip
6.3.4. Analog IP
6.3.4.1. For Integrated Circuits
6.3.4.2. For System-on-Chip
6.3.5. Mixed Signal IP
6.3.5.1. For Integrated Circuits
6.3.5.2. For System-on-Chip
6.3.6. Memory IP
6.3.6.1. For Integrated Circuits
6.3.6.2. For System-on-Chip
6.3.7. Data Converter IP
6.3.7.1. For Integrated Circuits
6.3.7.2. For System-on-Chip
6.3.8. General Purpose IC IP
6.3.9. SoC Processor IP
6.4. Peripheral Controllers and Others
6.4.1. Ethernet
6.4.1.1. Modem and Error Correction
6.4.1.2. Ethernet PHYs
6.4.2. HDMI
6.4.3. Controllers
6.4.3.1. Interconnect Controllers
6.4.3.2. SATA Controllers
6.4.3.3. Storage Controllers
6.4.3.4. DRAM Controllers
6.4.4. Power Management IC
6.4.5. Display Drivers
6.5. Processor Type
6.5.1. Applications Processor IP
6.5.2. Graphic Processor IP
6.5.3. Digital Signal Processor IP
7. Global Semiconductor IP Market - End Use Verticals Analysis
7.1. Introduction
7.2. Communications
7.3. Consumer Electronics
7.4. Medical
7.5. Automotive
7.6. Industrial
7.7. Defense
7.8. Others
8. Global Semiconductor IP Market - Geographic Analysis
8.1. Introduction
8.2. Americas
8.2.1. North America
8.2.2. Brazil
8.2.3. Argentina
8.2.4. Mexico
8.3. Europe
8.3.1. UK
8.3.2. France
8.3.3. Germany
8.4. APAC
8.4.1. China
8.4.2. South Korea
8.4.3. Japan
8.4.4. Australia
8.5. ROW
9. Market Entropy
9.1. New Product Launches
9.2. M&As, Collaborations, JVs and Partnerships
10. Investment Opportunities - Analysis by Target companies/customers, Capital Investments, ROI, Payback Period and Source of Funds.
11. Company Reports (Overview, Financials, SWOT Analysis, Developments, Product Portfolio)
11.1. Actions Semiconductor
11.2. Advanced Micro Devices
11.3. Aeroflex Gaisler
11.4. Agate Logic
11.5. Alchip
11.6. Allwinner Technology
11.7. Altera
11.8. Amkor Technology
11.9. Analog Devices
11.10. Anyka
11.11. Apple Inc.
11.13. ARM Holdings
11.14. ASIX Electronics
11.15. Atheros
11.16. Atmel
11.17. Axis Communications
11.18. Broadcom
11.19. Cambridge Silicon Radio
11.20. Cavium Networks
11.21. CEVA, Inc.
11.22. Cirrus Logic
11.23. Conexant
11.24. Core Logic
11.25. Cortina Systems
11.26. CPU Tech
11.27. Cypress Semiconductor
11.28. Infineon Technologies
11.29. Innova Card
11.30. Intel Corporation
11.31. Imagination Technologies
11.32. Faraday Technology
11.33. Freescale Semiconductor
11.34. Frontier Silicon Ltd
11.35. Horizon Semiconductors
11.36. Imagination Technologies
11.37. Lattice Semiconductor
11.38. LSI Corporation
11.39. Marvell Technology Group
11.40. MediaTek
11.41. Maxim Integrated Products
11.42. Mentor Graphics Inc
11.43. Mosaid Technologies Inc
11.44. MIPS Technologies
11.45. Mistletoe Technologies
11.46. MosChip Semiconductor Technology
11.47. MStar Semiconductor
11.48. Naksha Technologies
11.49. NuCORE Technology
11.50. NVIDIA
11.51. NXP Semiconductors (formerly Philips Semiconductors)
11.52. Palmchip Corporation
11.53. PMC-Sierra
11.54. Qualcomm
11.55. Rambus Inc
11.56. Redpine Signals
11.57. Renesas
11.58. Samsung Electronics
11.59. Sequence Design
11.60. Sharp
11.61. Sigma Designs
11.62. SigmaTel
11.63. Silicon Integrated Systems
11.64. Silicon Image
11.65. Sonics
11.66. Skyworks Solutions
11.67. SoC Technology
11.68. STATS ChipPAC
11.69. STMicroelectronics
11.70. ST-Ericsson
11.71. Synopsys
11.72. Telechips
11.73. Tensilica
11.74. Teridian Semiconductor
11.75. Texas Instruments
11.76. Transmeta
11.77. TranSwitch
11.78. Virage Logic
11.79. Xilinx
11.80. Zoran Corporation
12. Appendix
12.1. Abbreviations
12.2. Sources
12.3. Research Methodology
12.4. Bibliography
12.5. Compilation of Expert Insights
12.6. Disclaimer

Ordering:

Order by Fax - using the form below

Order by Post - print the order form below and send to

Research and Markets,
Guinness Centre,
Taylors Lane,
Dublin 8,
Ireland.
Fax Order Form
To place an order via fax simply print this form, fill in the information below and fax the completed form to 646-607-1907 (from USA) or +353-1-481-1716 (from Rest of World). If you have any questions please visit http://www.researchandmarkets.com/contact/

Order Information
Please verify that the product information is correct and select the format(s) you require.

Product Name: Smart Windows Market - Analysis and Forecast (2014 - 2020): By Technology (Passive, Active On-Demand, Photochromic, Thermochromic, PDLC, SPD, EC); By Application (Automotive, Commercial, Residential, Aerospace) and Geography

Web Address: http://www.researchandmarkets.com/reports/3339359/
Office Code: SCH32QNT

Product Formats
Please select the product formats and quantity you require:

<table>
<thead>
<tr>
<th>Quantity</th>
<th></th>
</tr>
</thead>
<tbody>
<tr>
<td>Electronic (PDF) - 1 - 5 Users:</td>
<td>USD 3850</td>
</tr>
<tr>
<td>Electronic (PDF) - Site License:</td>
<td>USD 4250</td>
</tr>
<tr>
<td>Electronic (PDF) - Enterprisewide:</td>
<td>USD 5850</td>
</tr>
</tbody>
</table>

Contact Information
Please enter all the information below in BLOCK CAPITALS

Title:  
Mr  [ ]  Mrs  [ ]  Dr  [ ]  Miss  [ ]  Ms  [ ]  Prof  [ ]
First Name:  

Email Address: *  

Job Title:  
Organisation:  
Address:  
City:  
Postal / Zip Code:  
Country:  
Phone Number:  
Fax Number:  

* Please refrain from using free email accounts when ordering (e.g. Yahoo, Hotmail, AOL)
Payment Information

Please indicate the payment method you would like to use by selecting the appropriate box.

☐ Pay by credit card: You will receive an email with a link to a secure webpage to enter your credit card details.

☐ Pay by check: Please post the check, accompanied by this form, to:
Research and Markets,
Guinness Center,
Taylors Lane,
Dublin 8,
Ireland.

☐ Pay by wire transfer: Please transfer funds to:
Account number 833 130 83
Sort code 98-53-30
Swift code ULSBIE2D
IBAN number IE78ULSB98533083313083
Bank Address Ulster Bank,
27-35 Main Street,
Blackrock,
Co. Dublin,
Ireland.

If you have a Marketing Code please enter it below:

Marketing Code: ____________________________

Please note that by ordering from Research and Markets you are agreeing to our Terms and Conditions at http://www.researchandmarkets.com/info/terms.asp

Please fax this form to:
(646) 607-1907 or (646) 964-6609 - From USA
+353-1-481-1716 or +353-1-653-1571 - From Rest of World